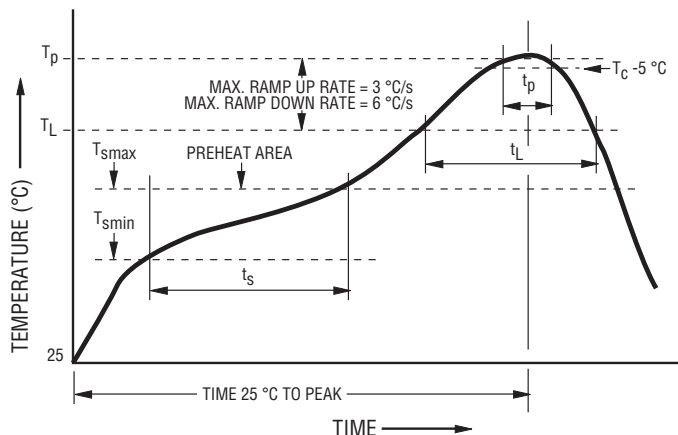
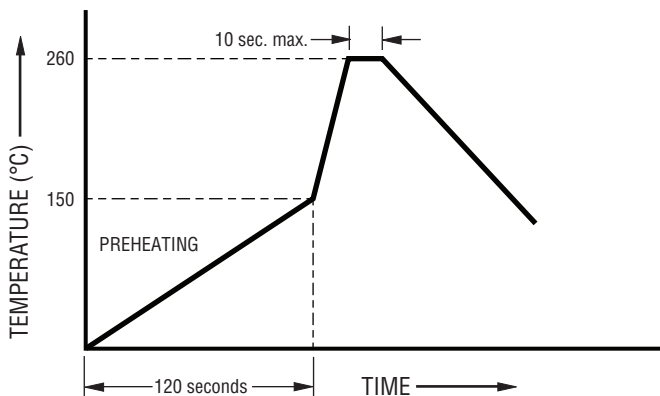


**Solder Reflow Recommendations**

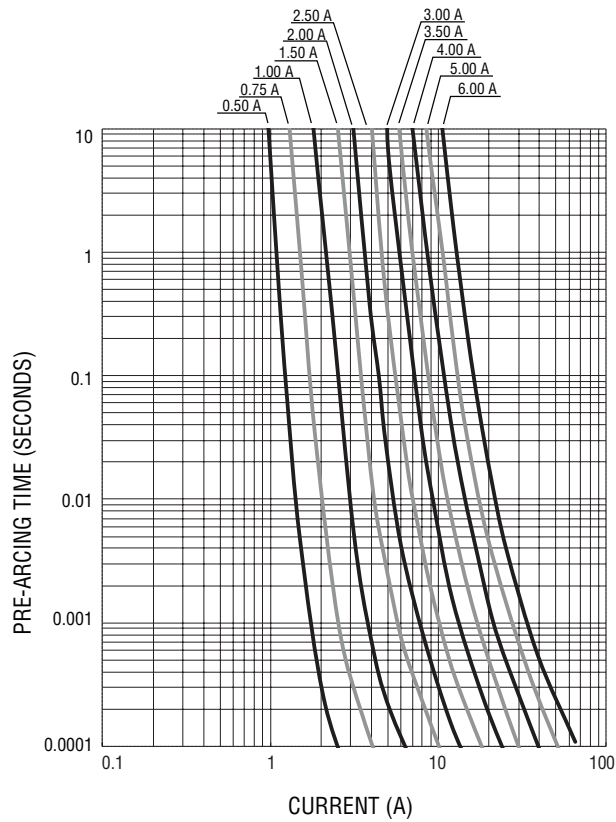
| Profile Feature                                                                                                                           | Pb-Free Assembly                   |
|-------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------|
| Preheat / Soak:<br>Temperature Min. ( $T_{smin}$ )<br>Temperature Max. ( $T_{smax}$ )<br>Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ ) | 150 °C<br>200 °C<br>60~120 seconds |
| Ramp Up Rate ( $T_L$ to $T_p$ )                                                                                                           | 3 °C / second max.                 |
| Liquidous Temperature ( $T_L$ )<br>Time ( $t_L$ ) maintained above $T_L$                                                                  | 217 °C<br>60~150 seconds           |
| Peak Package Body Temperature ( $T_p$ )                                                                                                   | 260 °C                             |
| Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_c$ )                                                         | 30 seconds*                        |
| Ramp Down Rate ( $T_p$ to $T_L$ )                                                                                                         | 6 °C / second max.                 |
| Time 25 °C to Peak Temperature                                                                                                            | 8 minutes max.                     |

\*Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

**Recommended Temperature Profile for Wave Soldering**

Wave soldering is suitable for 0603 size models.

Average Pre-Arcing Time Curves

Average  $I^2t$  vs.  $t$  Curves